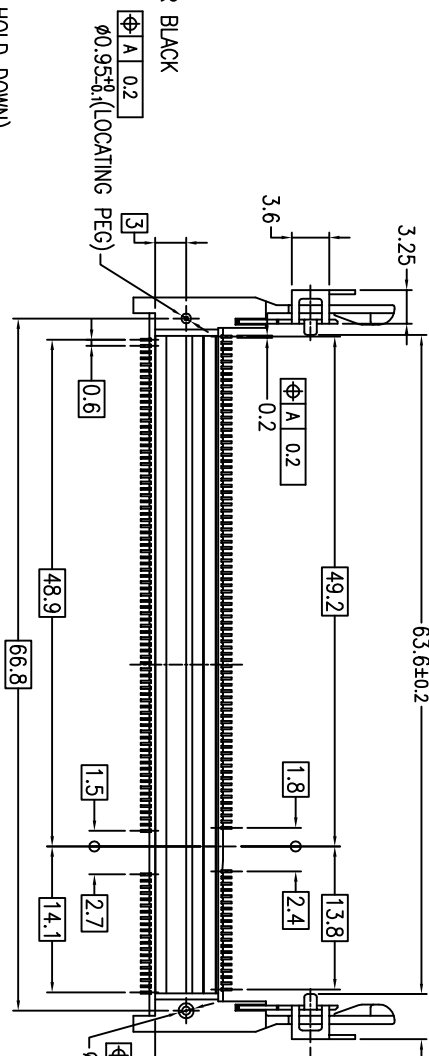
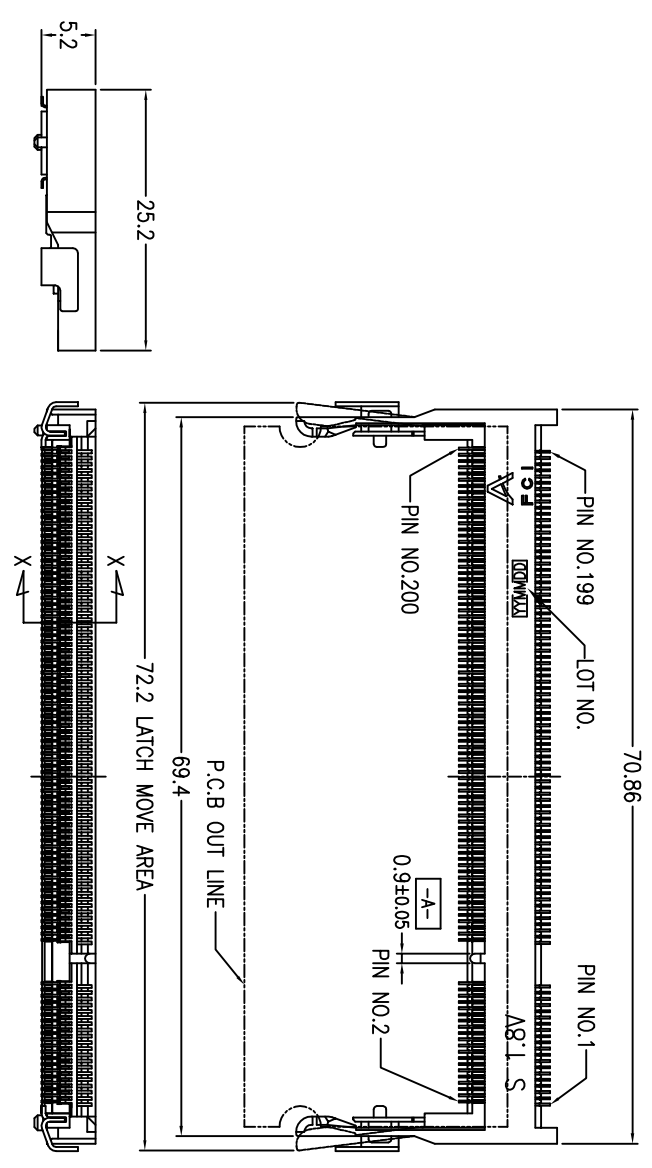




PRODUCT NO.  
10033853-52\*\*



- NOTE
1. PRODUCT SPEC. : GS-12-195
  2. PACKAGING SPEC. : GS-14-786
  3. MATERIAL
  - 1) HOUSING : LCP, UI94V-0, COLOR BLACK
  - 2) CONTACT : COPPER ALLOY
  - 3) HOLD DOWN : BRASS
  4. FINISH
  - 1) TERMINAL : SEE TABLE
  - 2) HOLD DOWN : SEE TABLE
  5. CO-PLANARITY : 0.1 MAX.(INCLUDE HOLD DOWN)
  6. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
  7. THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 10 SECONDS IN A REFLOW SOLDER APPLICATION.

mat'l. code	ech no	dr	date	tolerances unless otherwise specified	CUSTOMER COPY	projection	title
	2	M H	8/28/03	.XX ± 0.10		MM	DDR II 0.6 mm PITCH 200 POS. STANDARD TYPE ASSY
	3	M H	4/2/04				product family SOUF SO-DIMM code
	4	M H	6/29/04	0° ±5°			size dwg no 10033853
	A	J04-0401	M H	9/28/04	dr	engr	MHasegawa 6/29/04
	B	T05-0022	R C	11/9/04	chr		MHasegawa 6/29/04
	C	T05-0229	R C	10/12/05	chr		scale 2:1
	D	DC08-0333	B L	12/1/08	appr		
sheet	revision	D	D	D	D	D	
index	sheet	1	2	3	4		

ACAD

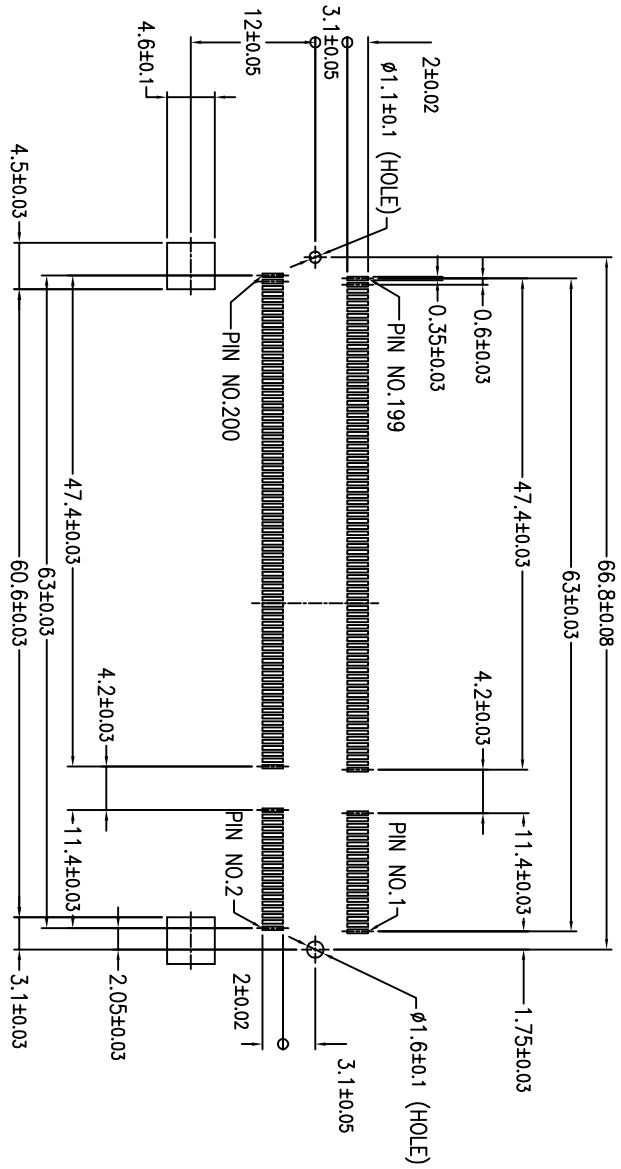
PDM: Rev:D

STATUS: Released

Printed: May 25, 2011



PRODUCT NO.  
10033853-52\*\*



RECOMMENDED MOUNTING P.C.B LAYOUT

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		FCI	
ltr	ecn no	dr	date	linear	.XX ± 0.10	projection	title
D				angles	0° ±5°	MM	DDR II 0.6 mm PITCH 200 POS. STANDARD TYPE ASSY
				dr	M.Hasegawa	6/29/04	product family
				engr	M.Hasegawa	6/29/04	SOUF SO-DIMM
				chr			code
				appd			10033853
sheet	revision			scale	2:1		sheet
index	sheet						2 of

ACAD

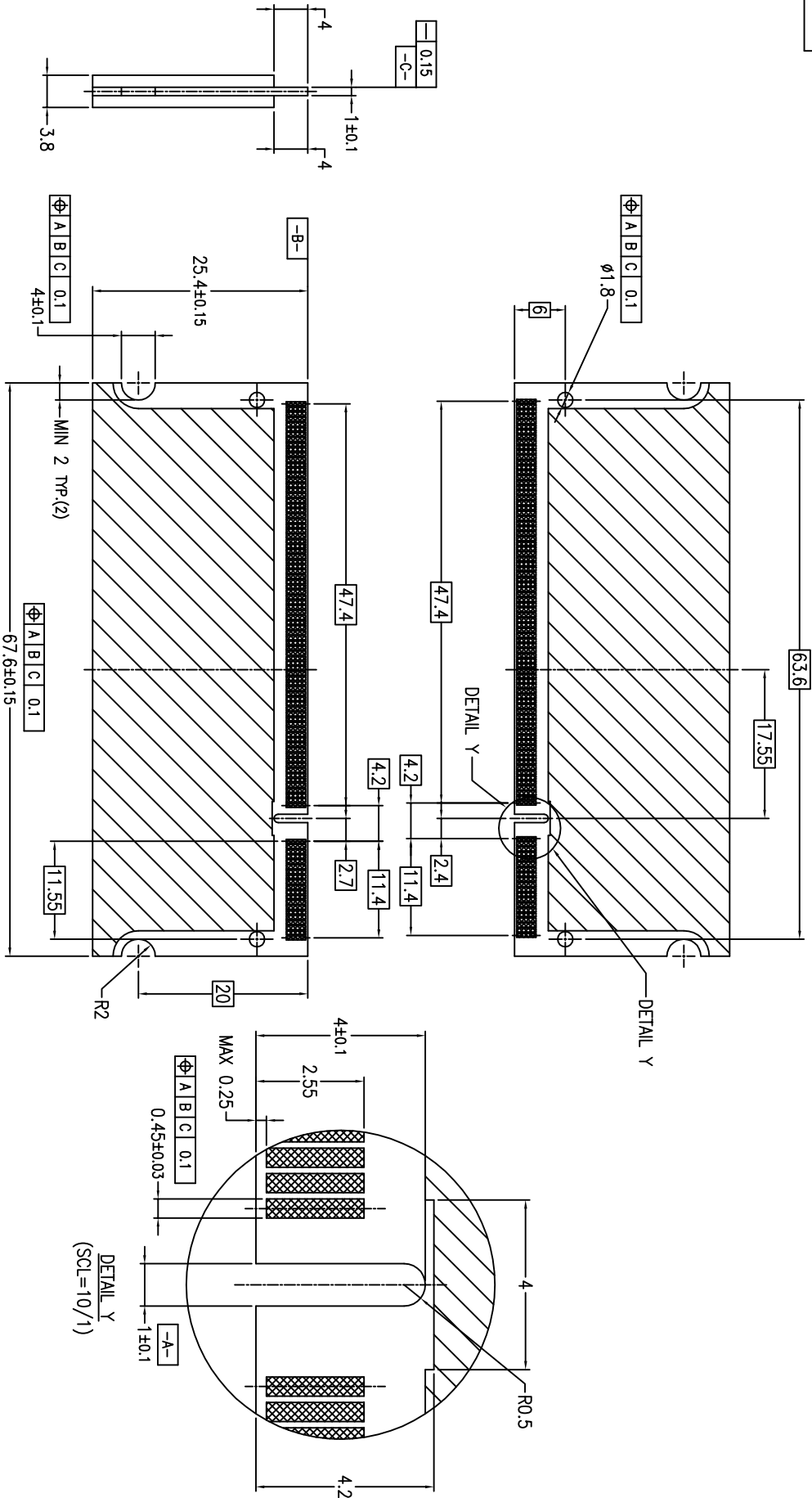
PDM: Rev:D

STATUS: Released

Printed: May 25, 2011



PRODUCT NO.  
10033853-52\*\*



RECOMMENDED MODULE P.C.B. LAYOUT

mat'l. code	tolerances unless otherwise specified	CUSTOMER COPY	title
D	.XX ± 0.10	projection	DDR II 0.6 mm PITCH 200 POS. STANDARD TYPE ASSY
linear	.XX ± 0.10	MM	product family SOUF SO-DIMM
angles	0° ±5°	scale	size dwg no 10033853
dr	M.Hosegawa		code JP
engr	M.Hosegawa		sheet 3 of
chr			
appd			
sheet index			
revision			
sheet			

ACAD

PDM: Rev:D

STATUS: Released

Printed: May 25, 2011



PRODUCT NO.	LOCATING PEG	TERMINAL CONTACT AREA FINISH	HOLD DOWN FINISH	SOLDER TAIL FINISH
10033853-052FSLF	YES	Au FLASH		
10033853-152FSLF	NO			
10033853-052TSLF	YES	Au 0.3um MIN.	PURE Sn PLATING	
10033853-152TSLF	NO			
10033853-052ASLF	YES	Au 0.76um MIN.		Au FLASH
10033853-152ASLF	NO			
10033853-052FB	NO			
10033853-152FB	YES	Au 0.3um MIN.	Sn-Pb PLATING	
10033853-052AB	NO			
10033853-152AB	YES	Au 0.76um MIN.		
10033853-252FSLF	YES	Au FLASH		
10033853-352FSLF	NO			
10033853-252TSLF	YES	Au 0.3um MIN.	Sn-Pb PLATING	
10033853-352TSLF	NO			
10033853-252ASLF	YES	Au 0.76um MIN.		Pure Sn PLATING
10033853-352ASLF	NO			
10033853-252FB	YES	Au FLASH		
10033853-352FB	NO			
10033853-252TSLF	YES	Au 0.3um MIN.	Sn-Pb PLATING	
10033853-352TSLF	NO			
10033853-252AB	YES	Au 0.76um MIN.		
10033853-352AB	NO			
10033853-452FS	YES	Au FLASH		
10033853-452TS	YES	Au 0.3um MIN.	PURE Sn PLATING	
10033853-452AS	YES	Au 0.76um MIN.		
10033853-452AS	NO			
10033853-452FB	YES	Au FLASH		
10033853-452FB	NO			
10033853-452TBL	YES	Au 0.3um MIN.	Sn-Pb PLATING	
10033853-452TBL	NO			
10033853-452TAB	YES	Au 0.76um MIN.		
10033853-452TAB	NO			

mat'l. code	tolerances unless otherwise specified			CUSTOMER COPY	 www.fciconnect.com
lfr	ecm no	dr	date	linear	
D				.XX ± 0.10	projection
				angles	0° ±5°
				dr	MHosegawa 6/29/04
				engr	MHosegawa 6/29/04
				chr	
				apppd	
sheet index	revision			scale	2:1
				product family	SOUF SO-DIMM
				size	10033853
				code	JP
				sheet	4 of

